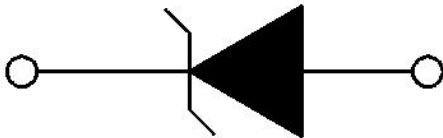


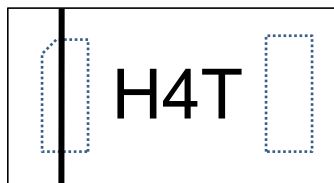
Features

- 2-pin lead-less package
- Junction capacitance (Max value: 650pF)
- Peak Pulse Current (8/20 μ s) Max: 185A
- IEC61000-4-2 (ESD) $\pm$ 30kV (air), $\pm$ 30kV (contact)
- Low clamping voltage
- Low leakage current
- Working voltages:4.5V
- RoHS Compliant

Appearance & S mbo



Uni-directional



H4T=Marking Code

Mechanica Characteristics

- Package: DFN1610-2L
- Lead Finish:Matte Tin
- Case Material: "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Tape Reel :3000pcs

Applications

- Mobile Phone, Digital cameras
- Battery Protection
- Power Line Protection
- Vbat pin for Mobile Devices
- Hand Held Portable Applications

Absolute Maximum Ratings (T=25°C, RH=45%-75%, unless otherwise specified)

Parameters	Symbol	Value	Unit
Peak Pulse Power (tp=8/20μs waveform)	P _{PP}	2775	W
Peak Pulse Current (8/20μs)	I _{PP}	185	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	±30 ±30	KV
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

Electrical Characteristics (T=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V _{RWM}				4.5	V
Reverse Breakdown Voltage	V _{BR}	I _R = 1mA	4.8		7	V
Reverse Leakage Current	I _R	V _R = 4.5V			0.2	μA
Clamping Voltage	V _C	I _{PP} = 1A, T _P =8/20us			7	V
Clamping Voltage	V _C	I _{PP} = 185A, T _P =8/20us			15	V
Junction Capacitance	C _J	V _R = 0V, f = 1MHz			650	pF

Typical Characteristics

FIG1: Power rating derating curve



FIG2: pulse Waveform



FIG3: Capacitance between terminals characteristics

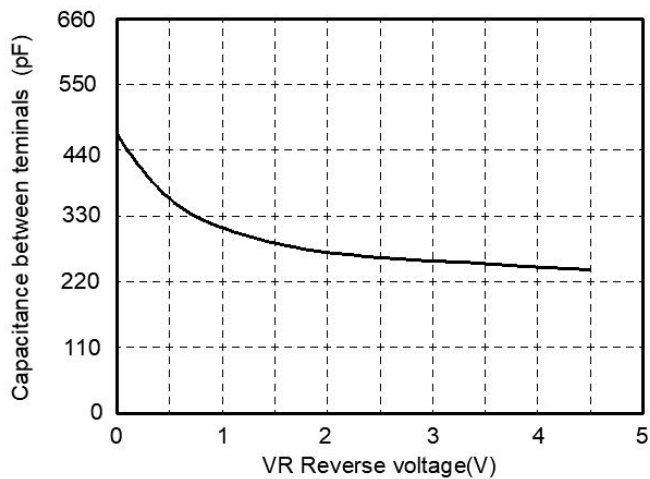
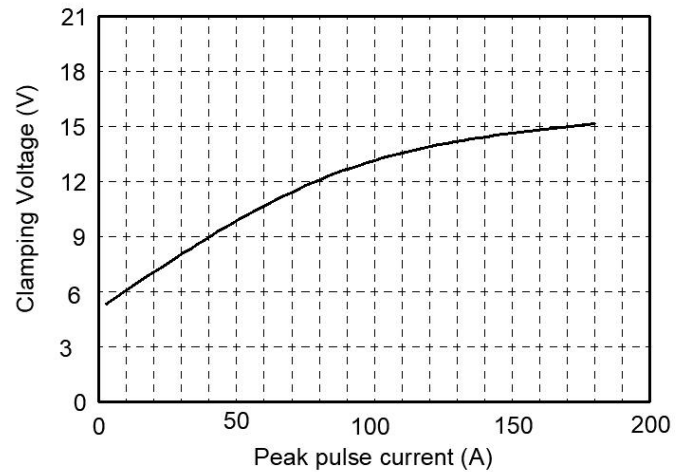
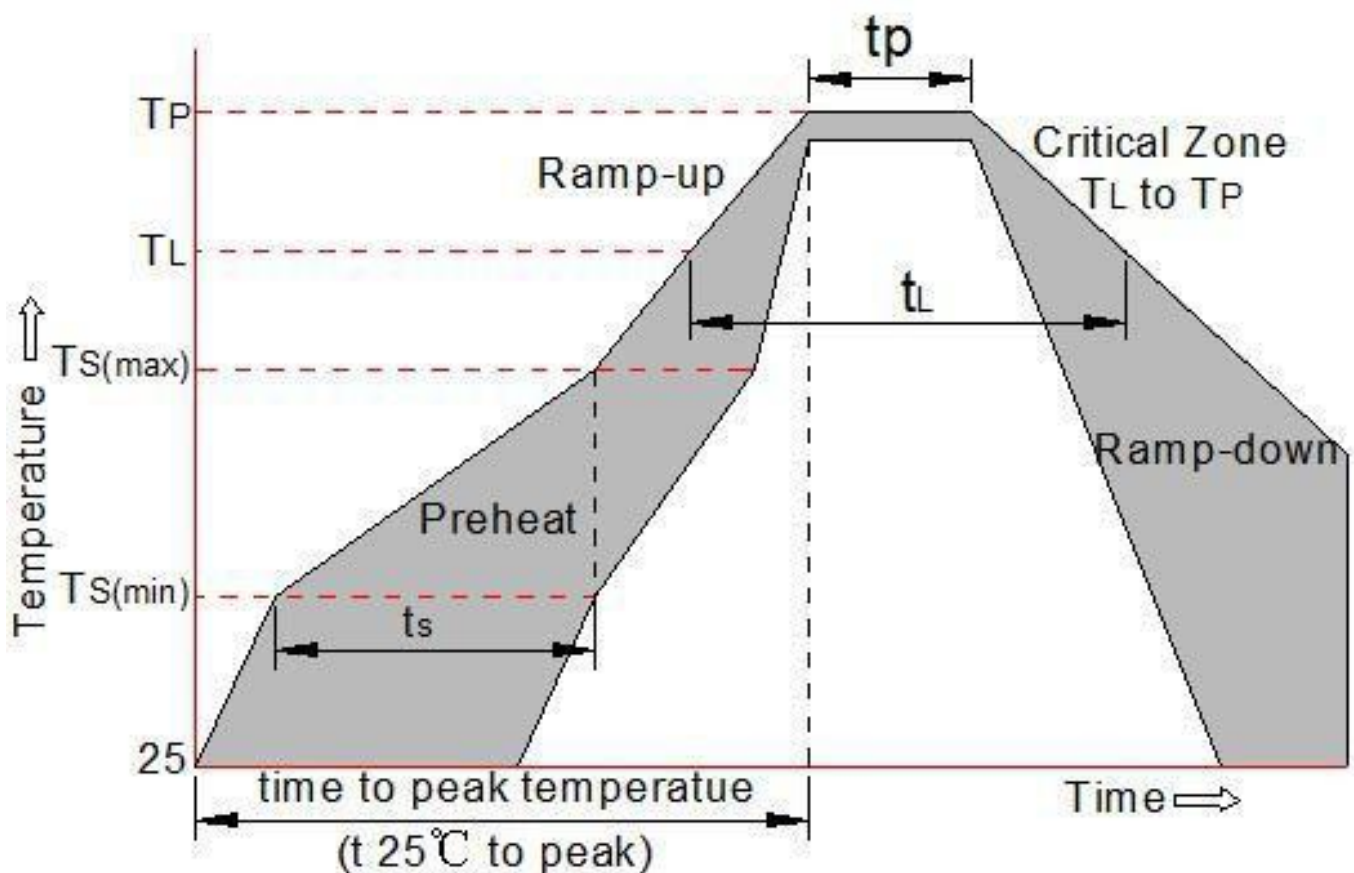


FIG4: Clamping Voltage vs. Peak Pulse Current

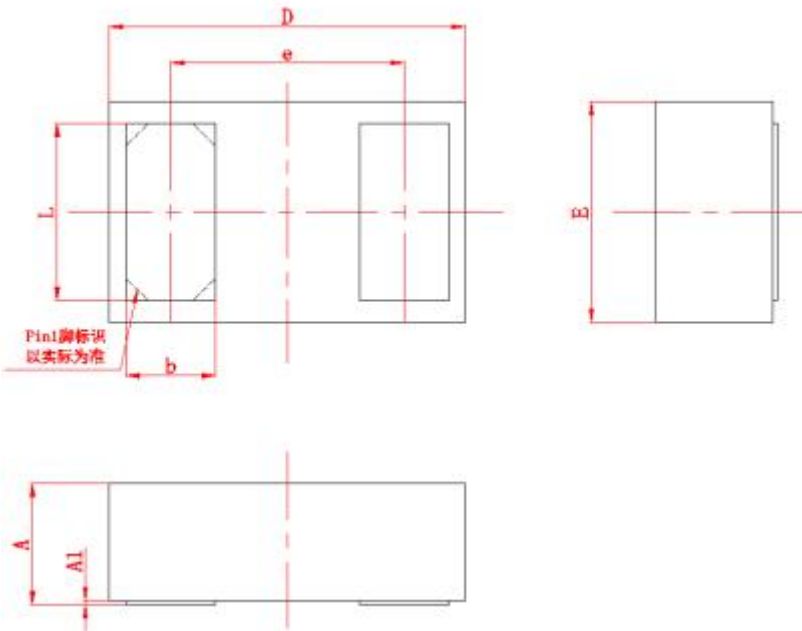


Soldering parameters

Reflow Condition		Pb-Free assembly see as bellow
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C

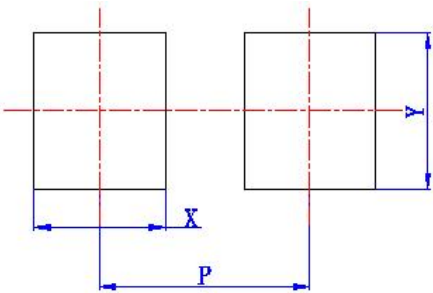


Package mechanical data



Symbol	Dimensions in millimeters	
	min	max
A	0.50	0.6
A1	0	0.05
D	1.5	1.7
E	0.9	1.1
e	(1.05)	
b	0.35	0.45
L	0.75	0.95

Suggested Land Pattern



Symbol	Dimension in Millimeters
	typ
X	(0.62)
Y	(1.0)
P	(1.2)